budatec®

Equipment for semiconductor and photovoltaic industries

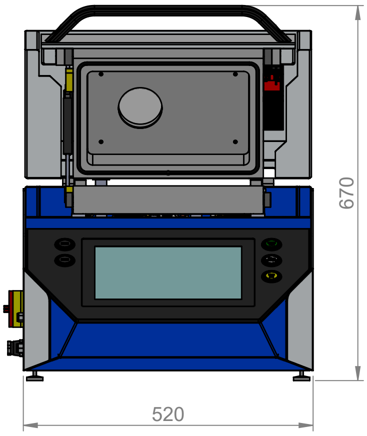
VS 160 S

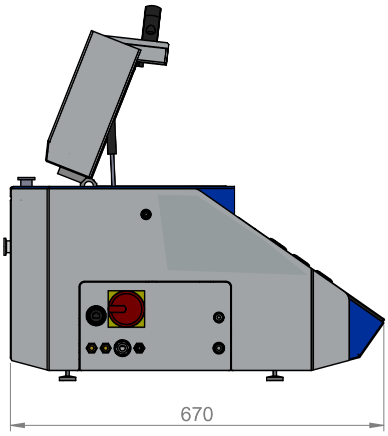
The next generation of Vacuum Soldering Systems

Soldering

Made in Berlin

Sintering





Technical Data

Plate size:	160 x 160 mm^2
Chamber height:	50 mm
Max. soldering temperature:	450 °C
Heating- / Coolingramp:	3 K/s
Max. load:	2,5 kg
Process atmosphere:	N_2
	N_2H_2 (95/5)
Power supply:	400 V / 16 A
Cooling Water:	10 slm

Features

- Gasflow programmable (inlet via proportional valve)
- Process-Control via separate thermocouples
- Graphical overview of process components
- Digital manual integrated in the software
- Maintenance reminder
- Proposal for changing necessary components at the end of lifetime